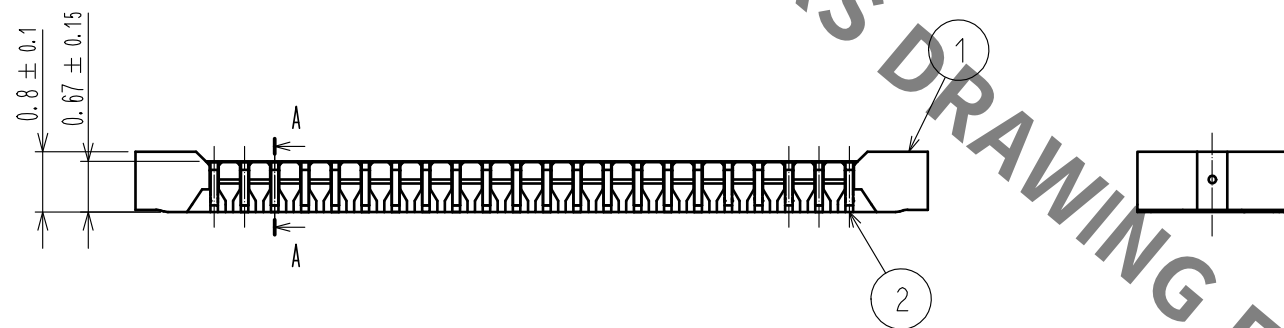
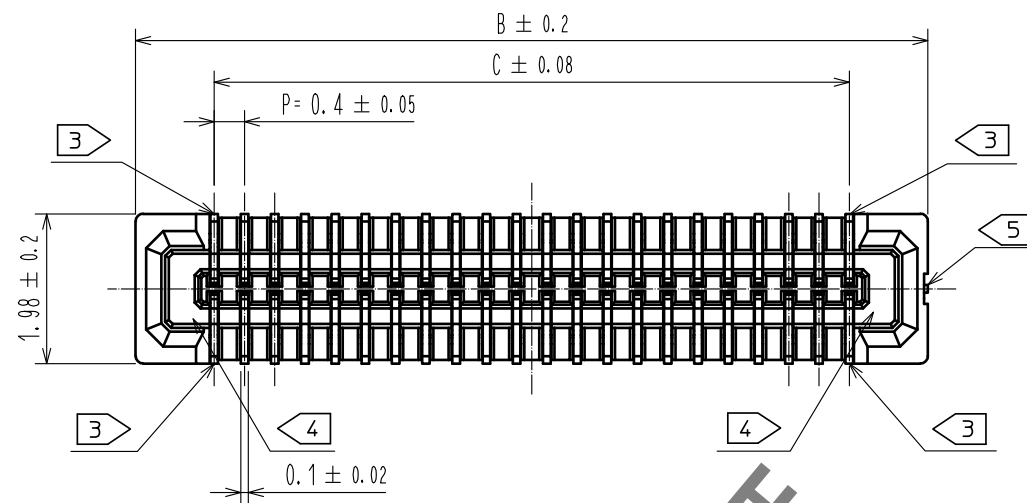




NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX

2. CONTACT PLATING SPECIFICATIONS.

CONTACT AREA : GOLD 0.05 μm MIN

SMT LEAD : GOLD 0.05 μm MIN

UNDERPLATING : NICKEL 1 μm MIN

(SURFACE : SEALING)

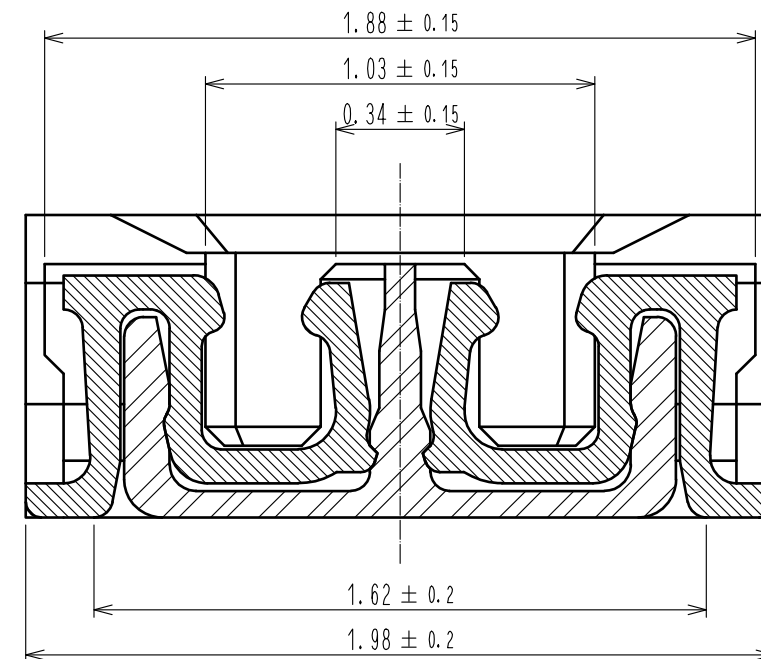
3. EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.

4. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

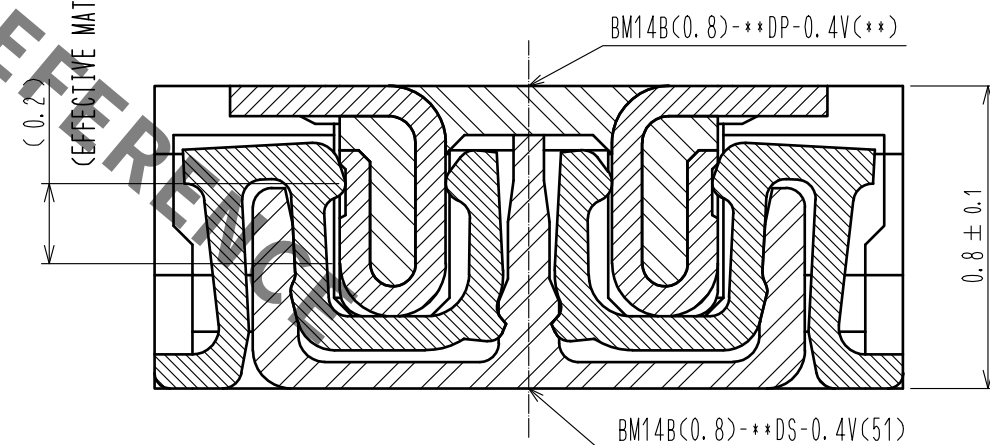
5. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

PART No.	CODE No.	B	C
BM14B(0.8)-10DS-0.4V(51)	CL684-8003-5-51	4.48	2.4
BM14B(0.8)-12DS-0.4V(51)	CL684-8041-4-51	4.88	2.8
BM14B(0.8)-20DS-0.4V(51)	CL684-8004-8-51	6.48	4.4
BM14B(0.8)-22DS-0.4V(51)	-	6.88	4.8
BM14B(0.8)-24DS-0.4V(51)	CL684-8005-0-51	7.28	5.2
BM14B(0.8)-30DS-0.4V(51)	CL684-8006-3-51	8.48	6.4
BM14B(0.8)-34DS-0.4V(51)	CL684-8007-6-51	9.28	7.2
BM14B(0.8)-40DS-0.4V(51)	CL684-8008-9-51	10.48	8.4
BM14B(0.8)-50DS-0.4V(51)	CL684-8009-1-51	12.48	10.4
BM14B(0.8)-60DS-0.4V(51)	CL684-8001-0-51	14.48	12.4

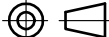
A-A (50:1)



ENGAGEMENT FIGURE (50:1)



3	PS	CLEAR (ENBOSSED CARRIER TAPE)		6	PS	CLEAR (REINFORCEMENT COLLAR)	
2	PHOSPHOR BRONZE	2		5	PS	BLACK (PLASTIC REEL)	
1	LCP	UL94 V-0, BLACK		4	POLYESTER	CLEAR (COVER TAPE)	
NO.	MATERIAL	FINISH . REMARKS		NO.	MATERIAL	FINISH . REMARKS	

UNITS mm		SCALE 10 : 1		COUNT 1	DESCRIPTION OF REVISIONS DIS-H-00003048	DESIGNED NY. YAMASHIRO	CHECKED TS. MIYAZAKI	DATE 17. 09. 29
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 HIROSE ELECTRIC CO., LTD.	APPROVED	: KH. IKEDA	09. 11. 24	DRAWING NO.	EDC3-322327-04		
	CHECKED	: WR. FUKUCHI	09. 11. 24	PART NO.	BM14B(0.8)-*DS-0.4V(51)		
	DESIGNED	: YH. HASEGAWA	09. 11. 20	CODE NO.	CL684		
	DRAWN	: YH. HASEGAWA	09. 11. 20				

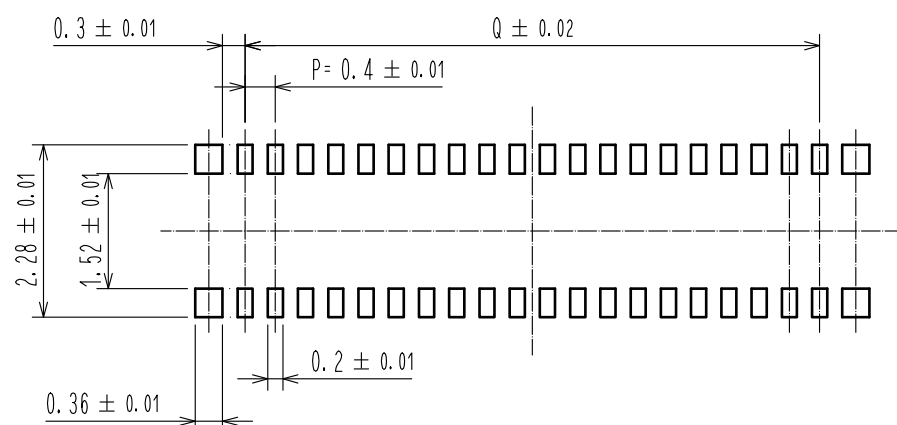
		
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Technical drawing of a 2xN grid of rectangular elements. The drawing includes the following dimensions and tolerances:

- Overall width: 0.3 ± 0.02
- Overall height: 2.28 ± 0.05
- Distance between the two rows: 1.48 ± 0.05
- Distance between the first and last element in a row: 0.41 ± 0.02
- Distance between the first and last element in a column: 0.2 ± 0.02
- Distance between the first and last element in a row (excluding the first and last elements): $P = 0.4 \pm 0.02$
- Distance between the first and last element in a column (excluding the first and last elements): $Q \pm 0.02$

The first and last elements in each row are shaded with diagonal lines, indicating they are grounding points. A legend at the bottom right shows a shaded square followed by the text ": GROUNDING".

METAL MASK THICKNESS : $100\text{ }\mu\text{m}$



PART No.	Q
BM14B(0.8)-10DS-0.4V(51)	1.6
BM14B(0.8)-12DS-0.4V(51)	2.0
BM14B(0.8)-20DS-0.4V(51)	3.6
BM14B(0.8)-22DS-0.4V(51)	4.0
BM14B(0.8)-24DS-0.4V(51)	4.4
BM14B(0.8)-30DS-0.4V(51)	5.6
BM14B(0.8)-34DS-0.4V(51)	6.4
BM14B(0.8)-40DS-0.4V(51)	7.6
BM14B(0.8)-50DS-0.4V(51)	9.6
BM14B(0.8)-60DS-0.4V(51)	11.6

TEMPERATURE (°C)

250

220

180

150

100

25

0

MAX 250 °C

220°C

180°C

150°C

TIME (SECONDS)

(60 SECONDS)

90~120 SECONDS

MAX 60 SECONDS

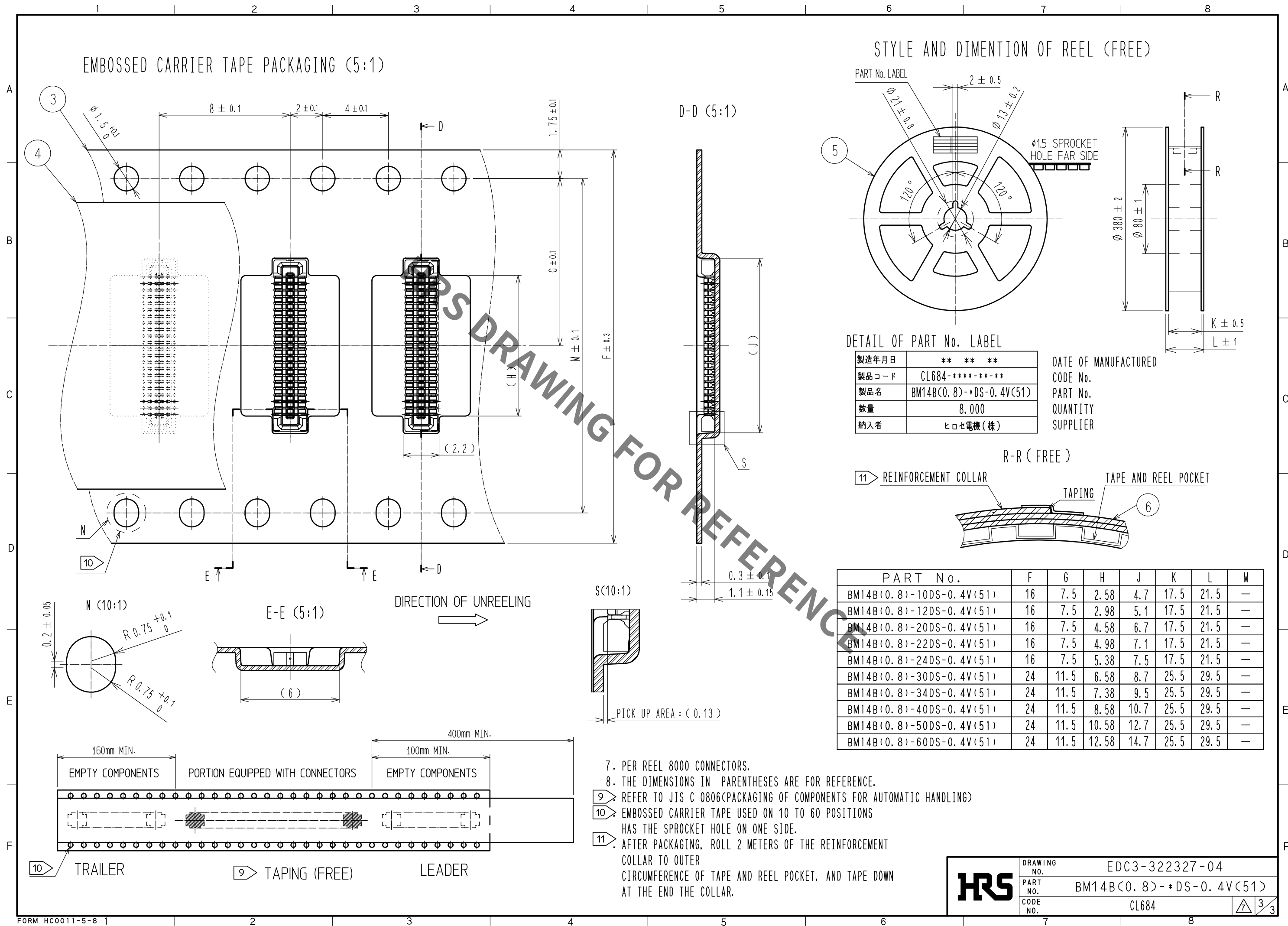
PRE-HEATING TIME

SOLDERING TIME

REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

- 1) REFLOW TIME
DURATION ABOVE 220℃, 60 SEC. MAX.
(PEAK TEMPERATURE: 250℃ MAX)
- 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150℃
PRE-HEAT TEMPERATURE(MAX): 180℃
PRE-HEAT TIME: 90-120 sec.

6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.



Mouser Electronics

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[BM14B\(0.8\)-60DS-0.4V\(51\)](#)